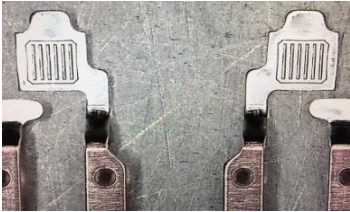
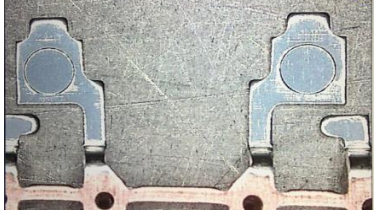

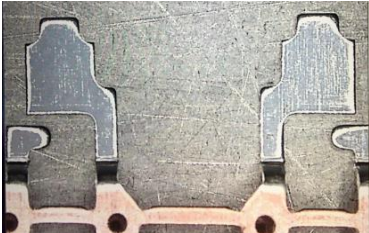




Title of Change:	Convert MCT6x series from Single to Matrix Leadframe.	
Proposed first ship date:	31 October 2019	
Contact information:	Contact your local ON Semiconductor Sales Office or <Kenny.Chan@onsemi.com>	
Samples:	Contact your local ON Semiconductor Sales Office or <PCN.samples@onsemi.com> Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.	
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <changkit.mok@onsemi.com>	
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>	
Change Part Identification:	It will be identified by implementation datecode.	
Change Category:	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____	
Change Sub-Category(s):	<input type="checkbox"/> Manufacturing Site Addition <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Site Transfer <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Other: _____	
Sites Affected:	ON Semiconductor Sites: None	External Foundry/Subcon Sites: Liteon Bangkok
Description and Purpose:		
The Matrix unit will be in		
1. Laser mark instead of inked mark 2. DAP for IR has changed to CIRCLE in Matrix LF for better dome shape control during coating process 3. Has an unique mold ID stamp		
Reason : Leadframe vendor would not want to continue with the support of non-matrix leadframe		
	Before Change Description	After Change Description
LeadFrame	Single (IR) X Y Dimension Spec (mm) : 1.32-1.48	Matrix (IR) Spec X Y Dimension Spec (mm) : 1.32-1.48
		
	Single (PTR) X Y Dimension Spec (mm) : 1.32-1.48	Matrix (PTR) X Y Dimension Spec (mm) : 1.32-1.48



		
Mold Compound	Without Mold ID	With Mold ID

	From	To
Product marking change	Ink Mark	Laser Mark

Reliability Data Summary:

DEVICE: MCT6

PACKAGE: PDIP 8 (Black Package)

Test	Specification	Condition	Interval	Results
HTOL	JESD22-A108	Ta=110°C, IF=20mA and IC=30mA biased	1008 hours	0/77
HTRB	JESD22-A108	Ta=110°C, VCE=30V biased	1008 hours	0/77
HTSL	JESD22-A103	Ta= 150°C, unbiased	1008 hours	0/77
PC	J-STD-020 JESD-A113	MSL 1@260°C	-	0/154
TC + PC	JESD22-A104	Ta= -55°C to +125°C	1000 cycles	0/77
H3TRB + PC	JESD22-A101	Ta=85°C / 85% RH, VCE=30V biased	1008 hours	0/77
AC	JESD22-A102	Ta=121°C / 100% RH / 15 psig, unbiased	96 hours	0/77
RSH	JESD22- B106	Ta = 265C, 10 sec	-	0/10
SD	JSTD002	Ta = 245C, 10 sec	-	0/10

Electrical Characteristic Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
MCT6SD	MCT6
MCT61S	
MCT62S	
MCT623S	



MCT623SD	MCT6
MCT6	
MCT61	
MCT62	
MCT62SD	
MCT61SD	
MCT6S	
MCT6W	